

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	4.5mΩ@10V	50A
	7mΩ@4.5V	

Feature

- Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

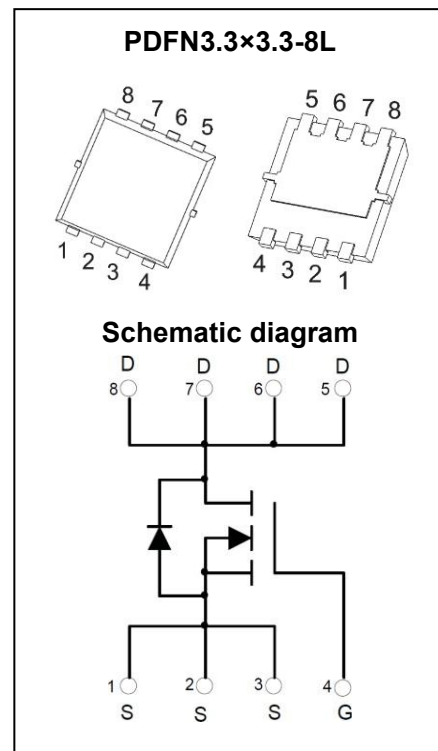
Application

- Power Switching Application

MARKING:



M080N03 = Device Code
 XX = Date Code
 Solid Dot = Green Indicator



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V_{DS}	30	V
Gate - Source Voltage		V_{GS}	±20	V
Continuous Drain Current ¹	$T_C = 25^\circ\text{C}$	I_D	50	A
	$T_C = 100^\circ\text{C}$	I_D	35.3	A
Pulsed Drain Current ²		I_{DM}	200	A
Single Pulsed Avalanche Current ³		I_{AS}	21	A
Single Pulsed Avalanche Energy ³		E_{AS}	110.25	mJ
Power Dissipation ⁵	$T_C = 25^\circ\text{C}$	P_D	25	W
Thermal Resistance from Junction to Ambient ⁶		$R_{\theta JA}$	35	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case		$R_{\theta JC}$	5	$^\circ\text{C/W}$
Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55~+150	$^\circ\text{C}$

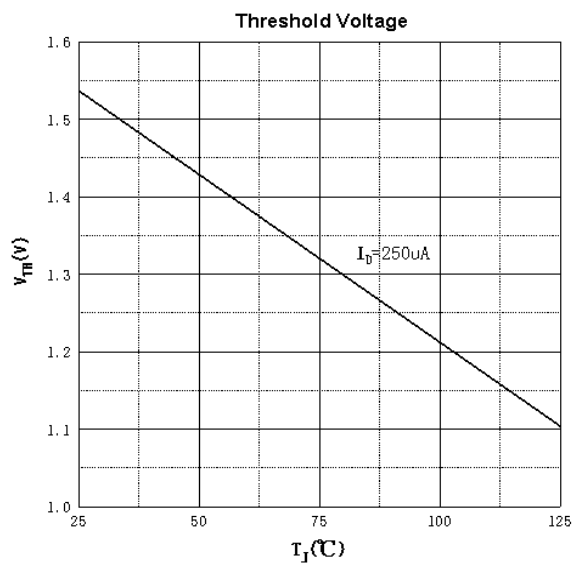
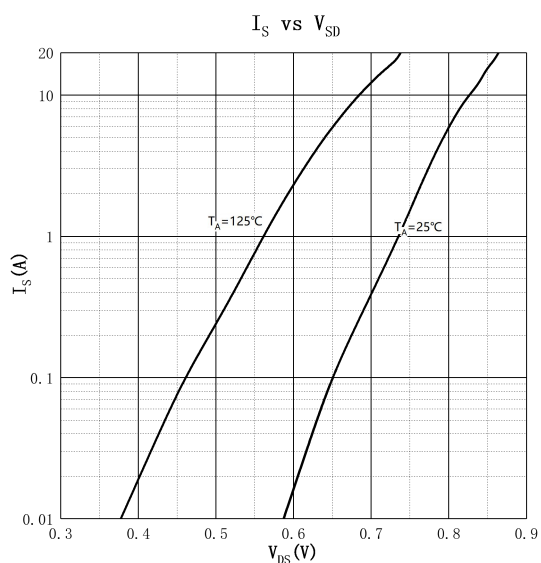
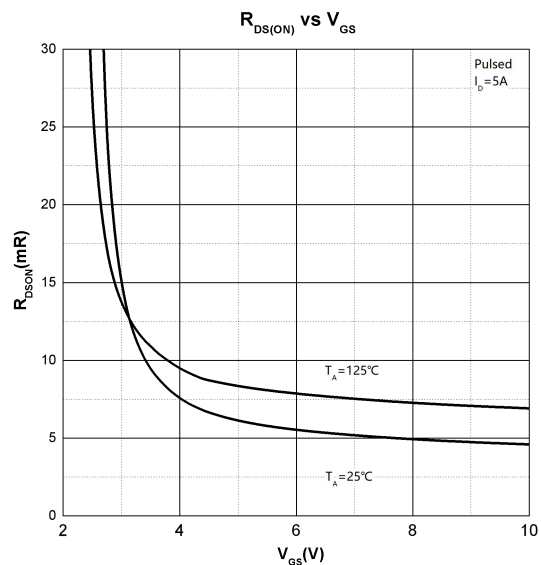
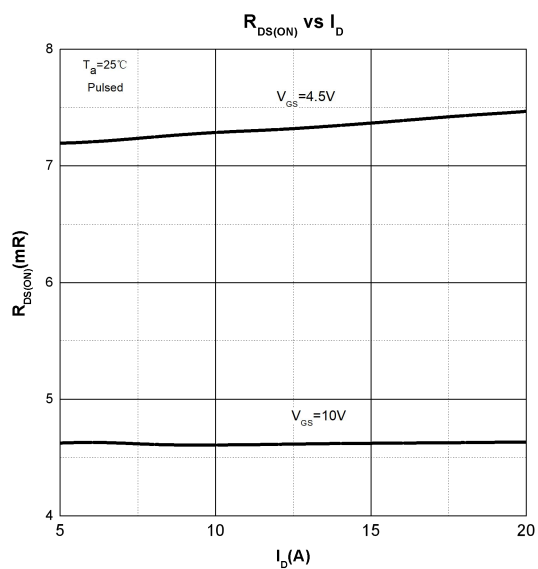
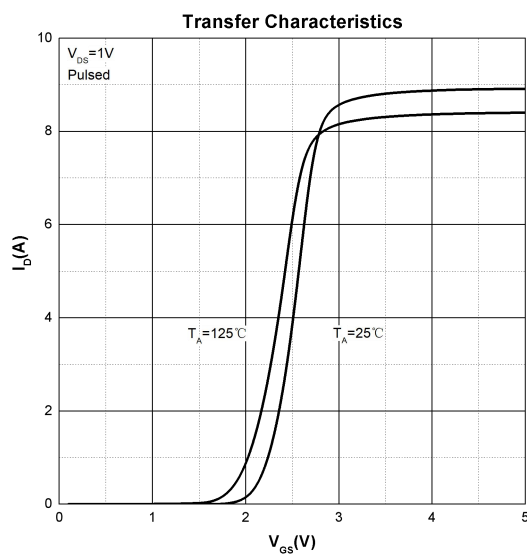
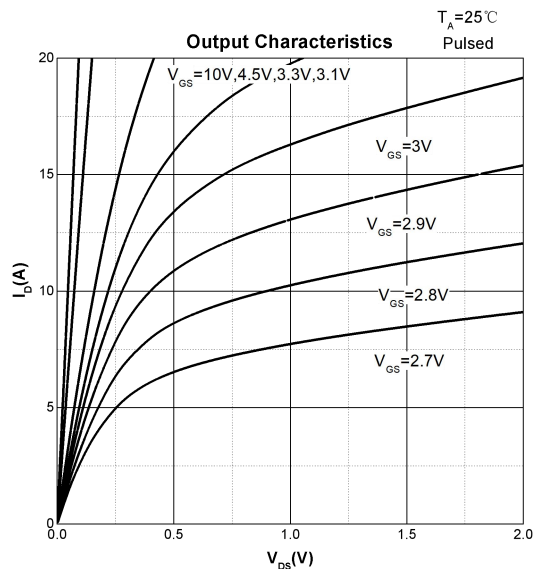
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

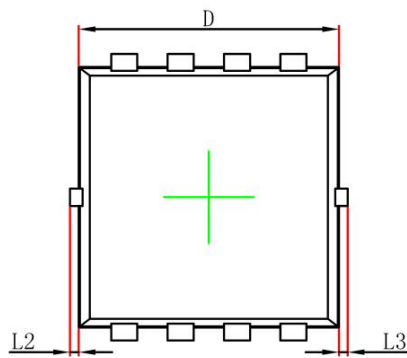
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1.0	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V			±100	nA
On Characteristics ⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.5	3.0	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 5A		4.5	6.5	mΩ
		V _{GS} = 4.5V, I _D = 5A		7.0	10.0	
Forward Transconductance	g _{FS}	V _{DS} = 10V, I _D = 10A				S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		1293		pF
Output Capacitance	C _{oss}			204.5		
Reverse Transfer Capacitance	C _{rss}			190.4		
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =15V,I _D =20A, V _{GS} =10V		32.3		nC
Gate-source Charge	Q _{gs}			4.9		
Gate-drain Charge	Q _{gd}			6.9		
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V,I _D =20A V _{GS} =10V,R _{GEN} =6Ω		9		ns
Turn-on Rise Time	t _r			8		
Turn-off Delay Ttime	t _{d(off)}			28		
Turn-off Fall Time	t _f			5		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = 5A		0.8	1.2	V
Diode Continuous Forward Current ¹	I _S	T _C = 25℃			50	A
Diode Pulse Forward Current ²	I _{SM}	T _C = 25℃			200	A

Notes :

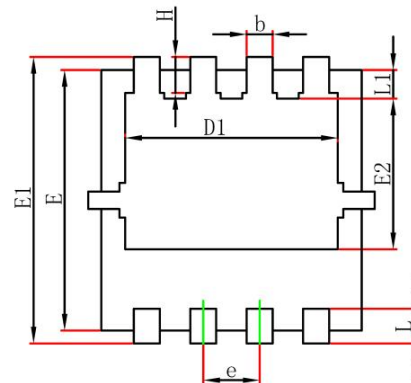
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = 25V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics

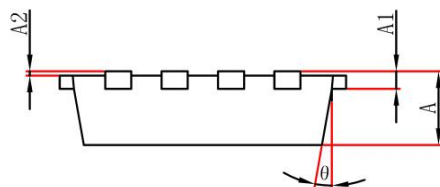


PDFN3.3×3.3-8L Package Information


Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°